

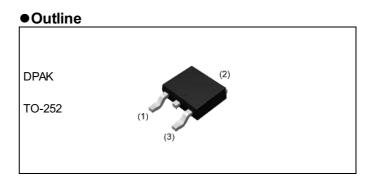
# Nch 100V 17.5A Power MOSFET

### Datasheet

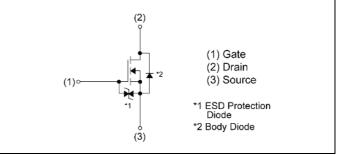
V <sub>DSS</sub>	100V
R <sub>DS(on)</sub> (Max.)	105mΩ
I <sub>D</sub>	±17.5A
P <sub>D</sub>	20W

### Features

- 1) Low on resistance
- 2) Fast switching speed
- 3) Drive circuits can be simple
- 4) Parallel use is easy
- 5) Pb-free lead plating ; RoHS compliant



#### Inner circuit



#### Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	330
_	Tape width (mm)	16
Туре	Basic ordering unit (pcs)	2500
	Taning and	TL
	Taping code	TL1
	Marking	RD3P175SN

#### • Absolute maximum ratings (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V <sub>DSS</sub>	100	V
Continuous drain current	۱ <sub>D</sub> *1	±17.5	А
Pulsed drain current	I <sub>DP</sub> *2	±35	Α
Gate - Source voltage	V <sub>GSS</sub>	±20	V
Power dissipation	P <sub>D</sub> *3	20	W
Junction temperature	Tj	150	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

Application

Switching

#### •Thermal resistance

Deremeter	Sumbol	Values			Linit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	$R_{thJC}^{*3}$	-	-	6.25	°C/W

# •Electrical characteristics (T<sub>a</sub> = 25°C)

Deremeter	Currente e l	Canditiana	Values			Unit	
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 1mA	100	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_j}$	I <sub>D</sub> = 1mA referenced to 25°C	-	116.9	-	mV/°C	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 100V, V <sub>GS</sub> = 0V	-	-	1	μA	
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS}$ = ±20V, $V_{DS}$ = 0V	-	-	±10	μA	
Gate threshold voltage	$V_{GS(th)}$	V <sub>DS</sub> = 10V , I <sub>D</sub> = 1mA	1.0	-	2.5	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$	I <sub>D</sub> = 1mA referenced to 25°C	-	-3.6	-	mV/°C	
		V <sub>GS</sub> = 10V, I <sub>D</sub> = 8.8A	-	75	105		
Static drain - source on - state resistance	R <sub>DS(on)</sub> *4	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 8.8A	-	80	112	mΩ	
		V <sub>GS</sub> = 4V, I <sub>D</sub> = 8.8A	-	85	119		
Gate resistance	R <sub>G</sub>	f = 1MHz, open drain	-	6.0	-	Ω	
Forward Transfer Admittance	Y <sub>fs</sub>   <sup>*4</sup>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 8.8A	5	-	-	S	

\*1 Limited only by maximum temperature allowed.

\*2 Pw $\leq$ 10µs , Duty cycle $\leq$ 1%

\*3 T<sub>C</sub>=25°C

\*4 Pulsed



# • Electrical characteristics ( $T_a = 25^{\circ}C$ )

Deremeter	Sympol	Conditions		Values		Lincit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	950	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	-	85	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	55	-	
Turn - on delay time	$t_{d(on)}^{*4}$	$V_{DD} \simeq 50V, V_{GS} = 10V$	-	10	-	
Rise time	t <sub>r</sub> *4	I <sub>D</sub> = 8.8A	-	25	-	20
Turn - off delay time	$t_{d(off)}^{*4}$	$R_L \simeq 5.7\Omega$	-	60	-	ns
Fall time	t <sub>f</sub> *4	R <sub>G</sub> = 10Ω	-	50	-	

# • Gate charge characteristics ( $T_a = 25^{\circ}C$ )

Parameter	Symbol	Conditions		Values		Unit
	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	$Q_g^{*4}$	V <sub>DD</sub> ≃ 50V,	-	24	-	
Gate - Source charge	Q <sub>gs</sub> *4	I <sub>D</sub> = 17.5A,	-	3	-	nC
Gate - Drain charge	${\sf Q}_{\sf gd}{}^{*4}$	V <sub>GS</sub> = 10V	-	6	-	

# •Body diode electrical characteristics (Source-Drain) ( $T_a = 25^{\circ}C$ )

Parameter	Symbol	Conditions	Values			Unit
Farameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Continuous forward current	۱ <sub>S</sub> *1	$T = 25^{\circ}$	-	-	17.5	А
Pulse forward current	$I_{SP}^{*2}$	T <sub>a</sub> = 25°C	-	-	35	А
Forward voltage	V <sub>SD</sub> *4	V <sub>GS</sub> = 0V, I <sub>S</sub> = 17.5A	-	-	1.5	V



# Fig.1 Power Dissipation Derating Curve

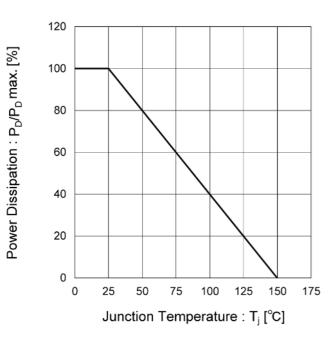


Fig.2 Maximum Safe Operating Area

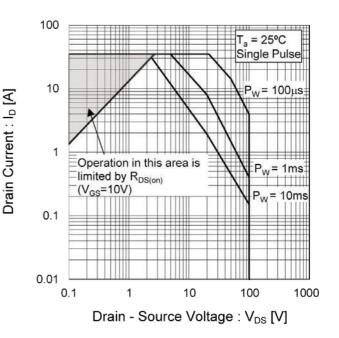
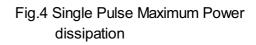
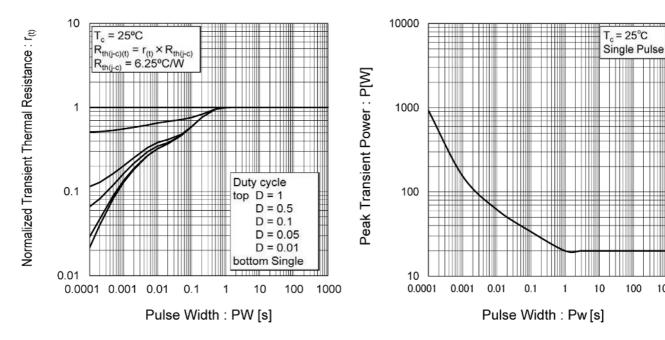


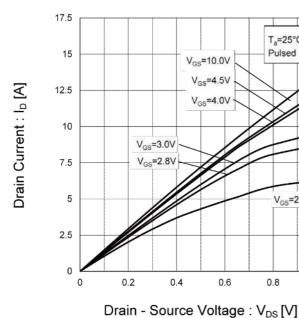
Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width







1000



## Fig.5 Typical Output Characteristics(I)

V<sub>GS</sub>=10.0V

V<sub>GS</sub>=4.5V

V<sub>GS</sub>=4.0V

T<sub>a</sub>=25°C

Pulsed

V<sub>GS</sub>=2.5V

1

0.8

Drain Current : I<sub>D</sub> [A]

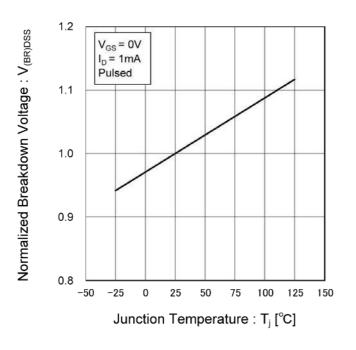
17.5 T<sub>a</sub>=25°C 15 Pulsed =10.0V V<sub>GS</sub>=4.5V V<sub>GS</sub>=4.0V 12.5 V<sub>GS</sub>=3.0V 10 V<sub>GS</sub>=2.8V V<sub>GS</sub>=2.5V 7.5 5 2.5 0 2 4 6 8 0 10 Drain - Source Voltage : V<sub>DS</sub> [V]

# Fig.6 Typical Output Characteristics(II)

Fig.7 Breakdown Voltage vs. **Junction Temperature** 

0.4

0.6





# Fig.8 Typical Transfer Characteristics

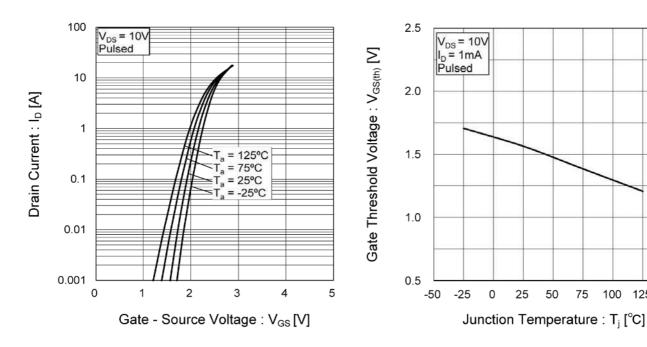
Fig.9 Gate Threshold Voltage vs. **Junction Temperature** 

75

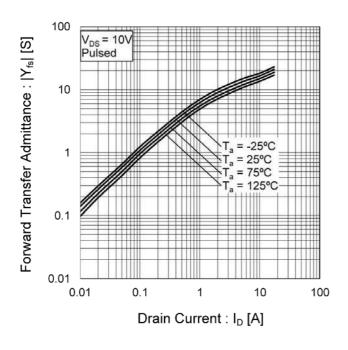
100

125

150



# Fig.10 Forward Transfer Admittance vs. **Drain Current**







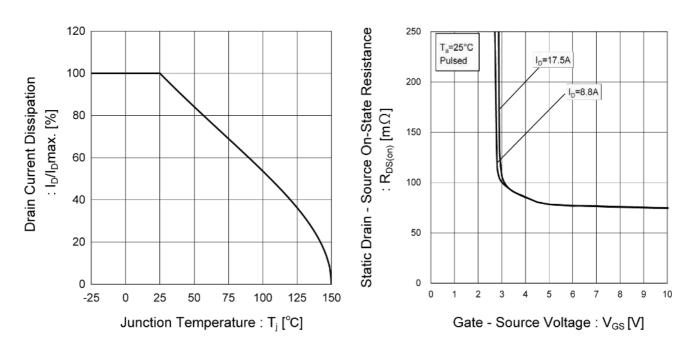


Fig.11 Drain Current Derating Curve

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

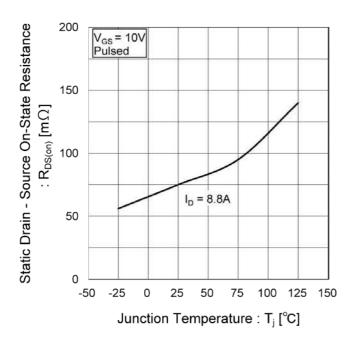






Fig.14 Static Drain - Source On - State

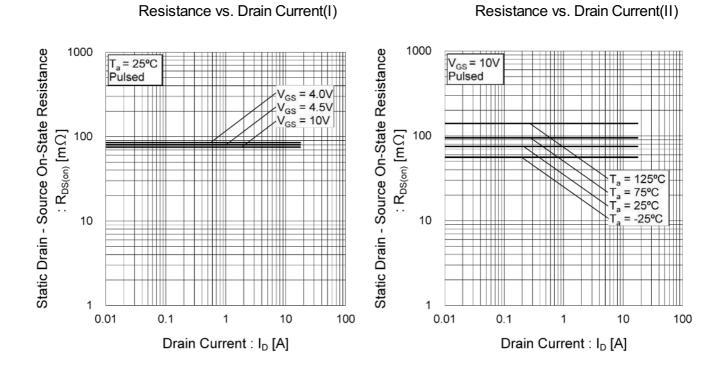
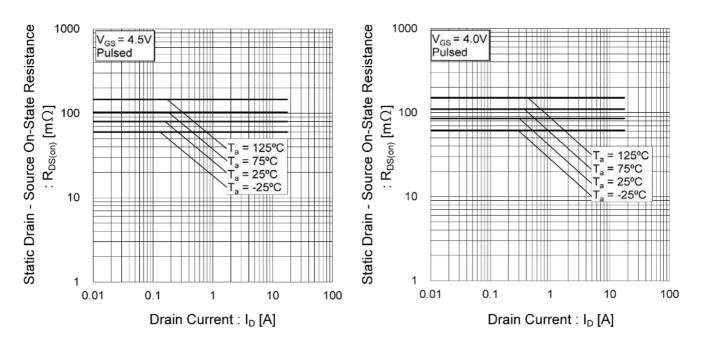
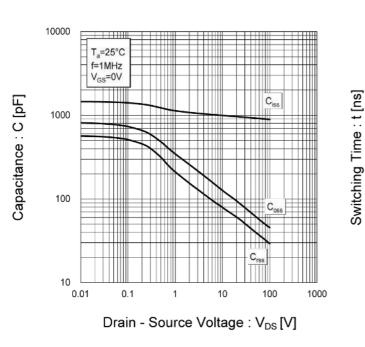


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current(III) Fig.17 Static Drain - Source On - State Resistance vs. Drain Current(IV)

Fig.15 Static Drain - Source On - State





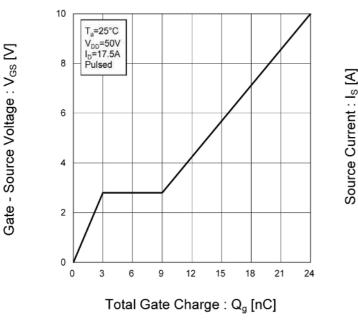


#### Fig.18 Typical Capacitance vs. Drain - Source Voltage

# Fig.19 Switching Characteristics

Fig.20 Dynamic Input Characteristics

Fig.21 Source Current vs. Source Drain Voltage



100  $V_{GS} = 0V$ Pulsed 10 = 125°C = 75°C = 25°C 1 -25°C 0.1 0.01 0.0 0.5 1.0 1.5 Source - Drain Voltage : V<sub>SD</sub> [V]



#### • Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

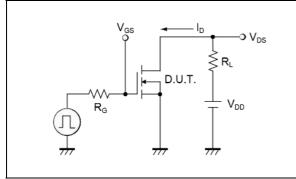


Fig.2-1 Gate Charge Measurement Circuit

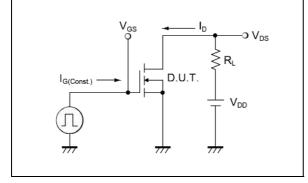
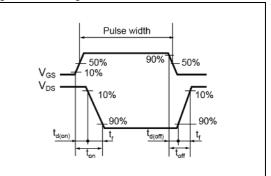
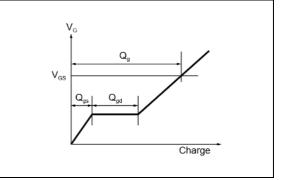


Fig.1-2 Switching Waveforms

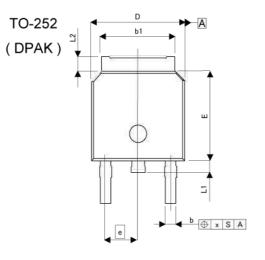


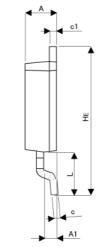


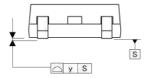


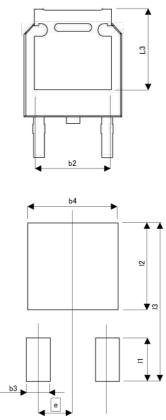


#### $\bullet \textit{Dimensions}(\mathsf{TL})$









Pattern of terminal position areas [Not a recommended pattern of soldering pads]

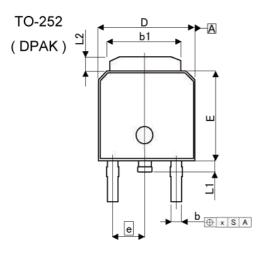
DIM -	MILIME	ETERS	INC	HES
	MIN	MAX	MIN	MAX
A	2.10	2.30	0.083	0.091
A1	0.70	1.10	0.028	0.043
b	0.65	0.85	0.026	0.033
b1	5.10	5.40	0.201	0.213
b2	5.	5.10		201
С	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.40	6.80	0.252	0.268
е	2.	30	0.091	
E	6.00	6.40	0.236	0.252
HE	9.50	10.50	0.374	0.413
L	2.	90	0.114	
L1	0.70	0.90	0.028	0.035
L2	0.70	1.30	0.028	0.051
L3	5.30		0.2	209
x	-	0.10	14	0.004
y	-	0.10	-	0.004

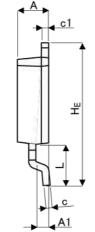
DIM -	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b3	<u> 1</u>	1.10	(14 <u>2</u> 3	0.043
b4		5.40	200	0.213
11	<u>u</u> :	2.90	W <u>5</u> 3	0.114
12		5.50	5 <del></del> )	0.217
13	5	10.50	1129	0.413

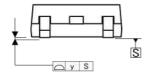
Dimension in mm/inches

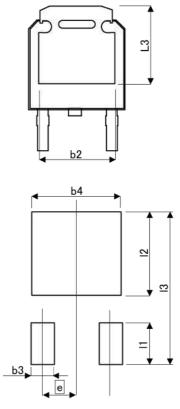


#### • Dimensions (TL1)









Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIME	ETERS	INCI	HES
DIM	MIN	MAX	MIN	MAX
A	2.20	2.40	0.087	0.094
A1	0.70	1.10	0.028	0.043
b	0.60	0.90	0.024	0.035
b1	5.20	5.50	0.205	0.217
b2	4.	80	0.1	89
С	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.40	6.80	0.252	0.268
e	2.30		0.0	)91
E	6.00	6.40	0.236	0.252
HE	9.40	10.40	0.370	0.409
L	2.	90	0.114	
L1	0.60	1.00	0.024	0.039
L2	0.70	1.30	0.028	0.051
L3	5.	30	0.209	
X	¥ j	0.25		0.010
у	70	0.10	0 <b>7</b> 35	0.004
DINA	MILIME	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
b3	8	1.15	( <b>4</b> 6	0.045
b4		5.55	6533	0.219
11	¥ (	2.77	2 (140)	0.109
12		5.50	25%	0.217
13	÷.	10.40	2 200	0.409

Dimension in mm/inches



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CLASSⅣ		CLASSⅢ	

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  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### **Precaution for Storage / Transportation**

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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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